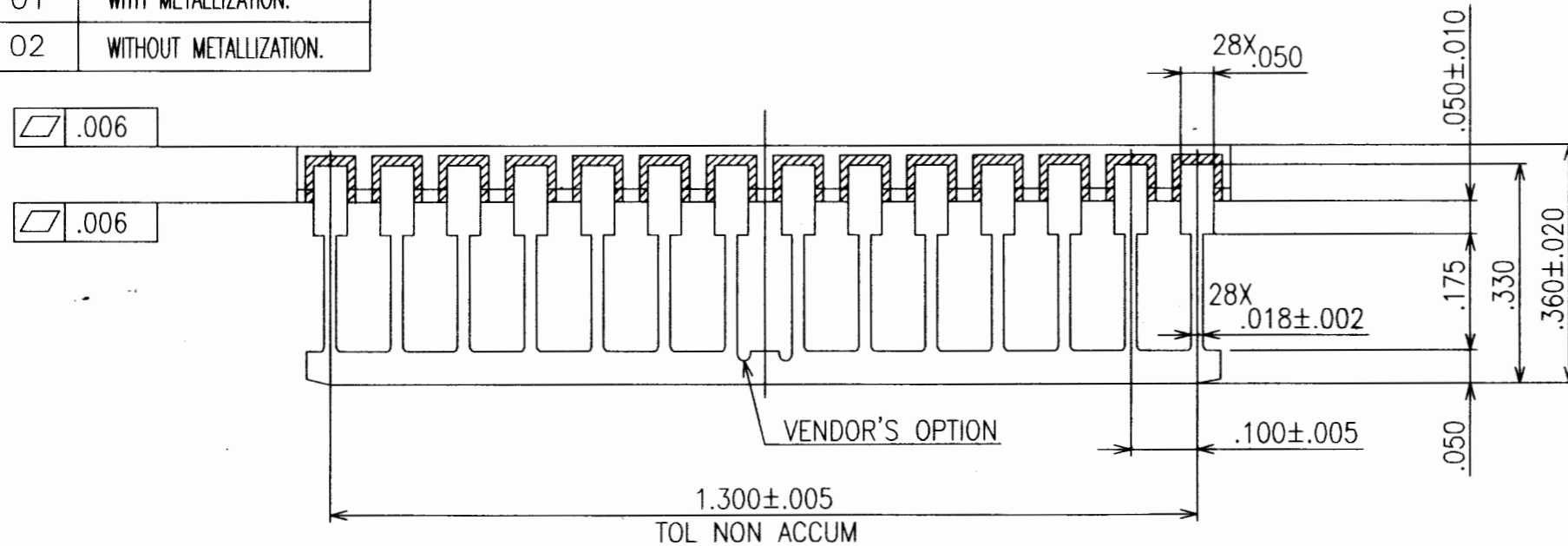
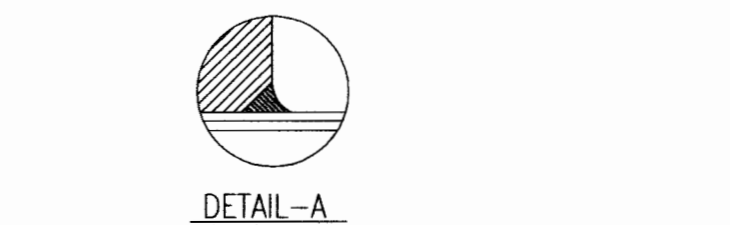


PART No.	NOTCH AREA METALLIZED
01	WITH METALLIZATION.
02	WITHOUT METALLIZATION.

INDEX MARK
(PLATING OPTION)



SB028M759-2		S=0	D=0
SB028M759-1		S=0	D=0
DRAWN	CHECKED	APPROVED	DATE
S.SE	S.T T.A	K.M	OCT.18.'92
DRAWING NO.		SHEET	
KD-S82759-B		1/2	

MODIFICATION	DATE	DRAWN	CHECKED	APPROVED
ADDED : PART No.02, CHANGED : SHEET No.2	DEC.06.'06	Y.H	Y.A	TO.H M.SU H.SA
REDRAWN : CONVERTED CAD DATA	OCT.18.'92	S.SE	S.T T.A	K.M
CHANGED	DATE	DRAWN	CHECKED	APPROVED

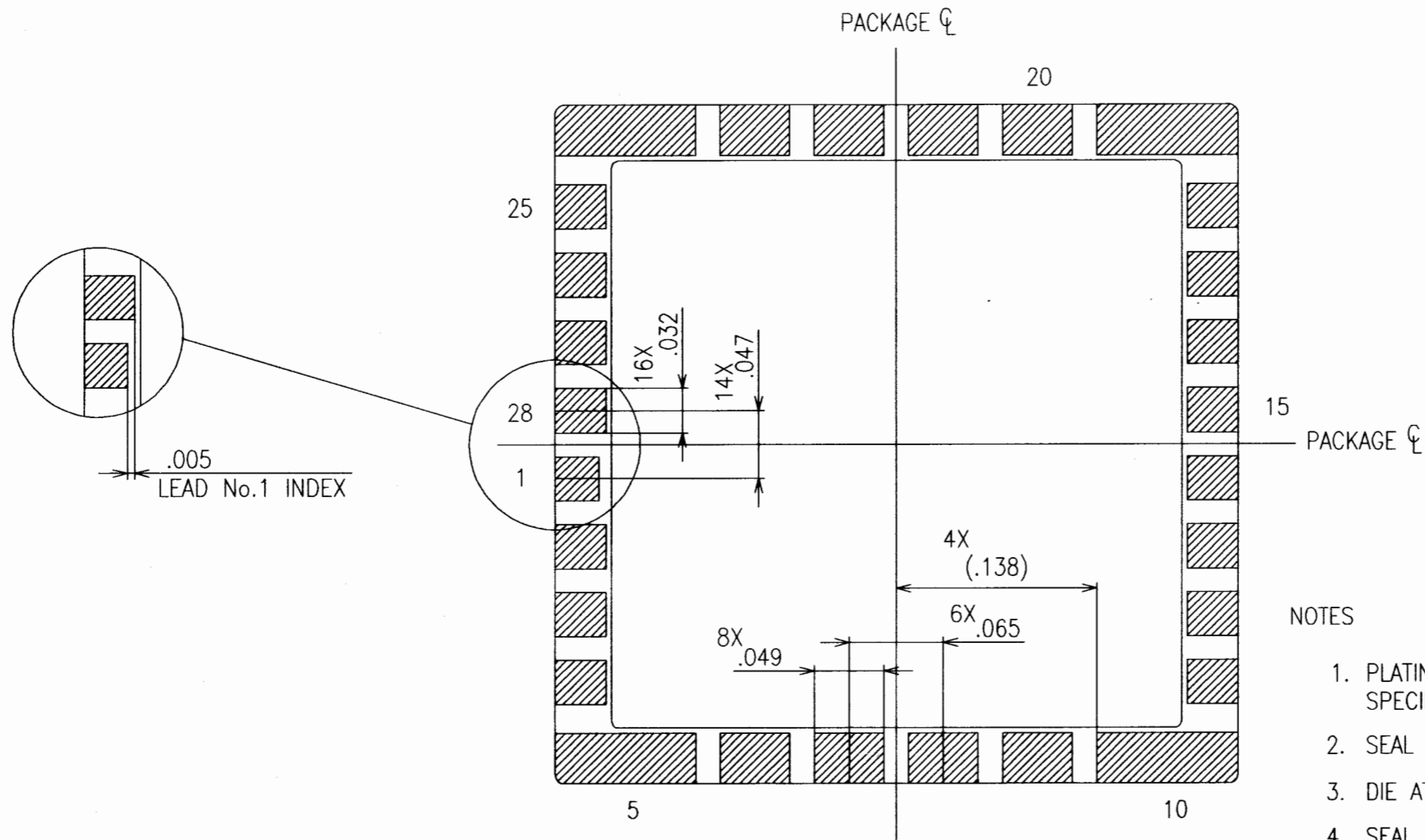
NAME
28 LEAD SIDE BRAZED PACKAGE

SCALE 4 / 1

MATERIAL
AS INDICATED

TOLERANCE
UNLESS OTHERWISE SPECIFIED
 $\pm .005$
THIRD ANGLE PROJECTION

KYOCERA CORPORATION
KYOTO JAPAN



BONDING PATTERN

NOTES

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY LEADS.
5. LEAD RESISTANCE: 0.35 OHM MAX.
- △ 6. WIRE BOND PAD CONNECTED TO CORRESPONDED OUTER LEAD.

MODIFICATION						NAME 28 LEAD SIDE BRAZED PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN S.SE	CHECKED S.T	APPROVED K.M	DATE OCT.18.'92
	△ B	ADDED : NOTE 6	DEC.06.'06	Y.H	TO.H	SCALE 10 / 1	THIRD ANGLE PROJECTION	<i>y. Hg</i>	<i>77b</i>		
	△ A	REDRAWN : CONVERTED CAD DATA CHANGED	OCT.18.'92	Y.A	M.SU	MATERIAL	KYOCERA CORPORATION KYOTO JAPAN	<i>y. Aoo</i>	<i>[Signature]</i>		DRAWING NO. KD-S82759-B
		DATE	DRAWN	CHECKED	APPROVED						